

IN THE CLAIMS:

Please edit the paragraph beginning on line 5 of page 9 as follows:

Patent Claims What is claimed is:

1. (Currently Amended). A [[M]]module bridge[[s]] system for smart labels for positioning chip modules (5) on carriers (12) and for the bridging connection of connection elements of the chip modules (5) to connection elements (11a, 11b) of antenna elements (11) arranged on or in the carriers (12), characterized in that the module bridge system comprising:
 - a carrier strip; and
 - a plurality of module bridges (10) are arranged one behind the other on [[a]]the carrier strip (1), wherein the carrier strip (1) has a plurality of depressions (2) arranged one behind the other for respectively receiving a chip module (5) assigned to a module bridge (10) and printed contact layers (7a, 7b), which cover the connection elements of the chip modules (5), with increased dimensions compared to the dimensions of the connection elements.
2. (Currently Amended). Module bridges according to The module bridge system of Claim 1, characterized in that further comprising: applied to the contact layers (7a, 7b) are adhesive layers (8a, 8b) applied to the printed contact layers (7a, 7b) for adhesively attaching individual module bridges (10) to the carriers (12) in the region of the connection elements (11a, 11b) of the antenna elements (11).
3. (Currently Amended). Module bridges according to The module bridge system of Claim 1, characterized in that wherein the printed contact layers (7a, 7b) are designed to be self-adhesive.
4. (Currently Amended). Module bridges according to any of Claims 1-3 characterized in that The module bridge system of Claim 1, wherein the printed contact layers (7a, 7b) consist of a first strip-like contact layer (7a) which extends in the a longitudinal direction of the carrier strip and covers the first connection elements of first connection sides (5a) of the chip modules (5),



and of a second strip-like contact layer (7b) which extends in the longitudinal direction of the carrier strip and covers the second connection elements of second connection sides (5b) of the chip modules (5).

5. (Currently Amended). ~~Module bridges according to The module bridge system of Claim 4, characterized in that~~ wherein the first and second strip-like contact layers (7a, 7b) have interruptions (4) between the chip modules (5), said interruptions extending in the width direction of the carrier strip.

6. (Currently Amended). ~~Module bridges according to any of Claims 2-5 characterized in that The module bridge system of Claim 2, wherein~~ the adhesive layers (8a, 8b) consist of two strip-like adhesive layers (8a, 8b) with interruptions (4), said layers running parallel to one another in the longitudinal direction of the carrier strip.

7. (Currently Amended). ~~Module bridges according to any of the preceding claims characterized in that The module bridge system of Claim 1, wherein~~ the chip modules (5) are arranged within the depressions (2) by means of adhesive (9a, 9b).

8. (Currently Amended). ~~Module bridges according to any of the preceding claims characterized in that The module bridge system of Claim 1, wherein~~ the depressions (2) have a sufficient depth for arranging the chip modules (5) therein in such a way that their upper sides (5c) and a surface (1a) of the carrier strip (1) which surrounds the depressions (2) lie in one plane.

9. (Currently Amended). ~~Module bridges according to any of the preceding claims characterized in that The module bridge system of Claim 1, wherein~~ the depressions (2) are shaped to be complementary to outer shapes of the chip modules (5) to be received therein.

10. (Currently Amended). ~~Module bridges according to any of the preceding claims characterized in that The module bridge system of Claim 1, wherein~~ the depressions (2) in each case have at least one hole on the underside.

11. (Currently Amended). ~~Module bridges according to any of the preceding claims characterized in that The module bridge system of Claim 1, wherein~~ the transport strip (1) has rows of holes (3) at the edge for the engagement of transport elements.

12. (Currently Amended). ~~Module bridges according to any of the preceding claims characterized in that~~ The module bridge system of Claim 1, wherein the carrier strip (1) is made of at least one of a deformable plastic[[s]] and/or paper material.

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